L Number	Hits	Search Text	DB	Time stamp
1	5148	(257/211,266,324,635,700,758).CCLS.	USPAT;	2003/10/08 13:52
1			US-PGPUB;	
[			EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
2	6124	(438/118,128,129,216,261,591,593,622).CCLS.	USPĀT:	2003/10/08 13:53
1		, ( · · · · · · · · · · · · · · · · · ·	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
}			IBM_TDB	
4	0	((438/118,128,129,216,261,591,593,622).CCLS.) and 'multiple-chip'	USPAT;	2003/10/08 13:54
			US-PGPUB;	
1			EPO, JPO,	
1			DERWENT;	
1	,		IBM_TDB	
3	4	((257/211,266,324,635,700,758).CCLS.) and 'multiple-chip'	USPĀT;	2003/10/08 13:55
		, , , , , , , , , , , , , , , , , , , ,	US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT;	
ĺ			IBM_TDB	
5	10890	multiple-chip multi near chip	USPAT;	2003/10/08 13:55
			US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
]			IBM_TDB	
6	245	multiple-chip	USPAT;	2003/10/08 14:12
			US-PGPUB;	
j j			ЕРО; ЛРО;	
l i			DERWENT;	
			IBM_TDB	
7	7	(first adj chip and second adj chip) with circuit near surface	USPAT;	2003/10/08 13:58
		( · · · · · · · · · · · · · · · · · · ·	US-PGPUB;	
]			ЕРО; ЛРО;	
}			DERWENT;	
			IBM_TDB	
8	585 <i>5</i>	first adj wiring and second adj wiring	USPAT;	2003/10/08 13:58
			US-PGPUB;	
			ЕРО; ЛРО;	
			DERWENT,	i
. i			IBM_TDB	
9	481	(first adj wiring and second adj wiring) with semiconductor adj substrate	USPAT,	2003/10/08 14:00
			US-PGPUB;	
			EPO; JPO;	
Ì			DERWENT,	
			IBM_TDB	
10	0	(((firs tadj chip) near3 surface) and ((second adj chip) near3 surface))	USPAT;	2003/10/08 14:03
1	1	with confront\$3	US-PGPUB;	
į	Į		ЕРО; ЛРО;	
			DERWENT;	
<u> </u>	ļ		IBM_TDB	
11	4	(("6402463") or ("6429528")).PN.	USPAT;	2003/10/08 14:04
ì			US-PGPUB,	
			EPO; JPO;	
			DERWENT;	
İ			IBM_TDB	
12	2	("6403463").PN.	USPĀT;	2003/10/08 14:06
}	Ì		US-PGPUB;	
ļ			ЕРО, ЛРО;	ļ
İ			DERWENT,	
j	}		IBM_TDB	

13	T 1	09/956973	USPAT;	2003/10/08 14:07
			US-PGPUB;	
			ЕРО; ЛРО;	
l			DERWENT,	
			IBM_TDB	İ
14	4	((257/211,266,324,635,700,758).CCLS.) and multiple-chip	USPAT;	2003/10/08 14:13
			US-PGPUB;	
	1		EPO; JPO;	}
			DERWENT;	
1	}		IBM_TDB	
15	49	multiple-chip and Stack\$4	USPAT;	2003/10/08 14:26
			US-PGPUB;	
			ЕРО; ЛРО;	l l
	l .		DERWENT;	
}	1		IBM_TDB	
16	1	(multiple-chip and Stack\$4) and lsi	USPAT;	2003/10/08 14:26
	i '		US-PGPUB;	1
			EPO; JPO;	
ì	ì '		DERWENT;	}
	<u> </u>		IBM_TDB	
17	23	(multiple-chip and Stack\$4) and bus	USPAT;	2003/10/08 14:27
	[		US-PGPUB;	
	1		ЕРО; ЈРО;	
			DERWENT;	
	1		IBM_TDB	